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1200V 75A CoolFAST™ 7 Technology IGBT

Part No.: HM75N120FT3
Package: TO-247Plus-3L

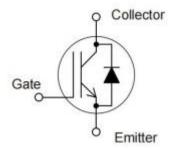
Features:

- Low Switching Power Loss
- Low Switching Surge and Noise
- Advanced Field Stop Technology
- Low EMI
- Maximum Junction Temperature 175°C
- Qualified According to JEDEC For Target Applications
- Pb-free Lead Plating, Halogen-free Mold Compound, RoHS Compliant



Applications:

- Industrial UPS
- Welding Machine
- Solar Converters
- Energy Storage
- EV Charger



Key Performance and Package Parameters

Type	Vce	Ic	VCEsat,Tvj=25℃	Tvjmax	Marking	Package
HM75N120FT3	1200V	75A	1.6V	175℃	HM75N120FT3	TO-247Plus-3L

Maximum Ratings and Characteristics

Absolute Maximum Ratings at Tvj= 25°C (unless otherwise specified)

Items	Symbols	Value	Units
Collector-emitter voltage	Vces	1200	V
Gate-emitter voltage Transient gate-emitter voltage (t _p ≤ 10µs, D< 0.010)	V _{GES}	±20 ±30	V
DC collector current, limited by T _{vjmax} T _C = 25°C T _C = 100°C	lc	150 75	A
Pulsed collector current, tp limited by Tylmax	ICP	300	Α
Diode forward current, limited by T _{vjmax} T _C = 25°C T _C = 100°C	l _F	150 75	А
Diode Pulsed collector current, to limited by Tymax	IFP	300	Α
Short circuit withstand time, V _{GE} = 15V, V _{CE} ≤ 600V	Tsc	5	μѕ
IGBT max. power dissipation	P _{D_IGBT}	750	W
FWD max. power dissipation	Po_FWO	500	W
Operating junction temperature	Tvj	-40 ~ +175	°C
Storage temperature	T _{stg}	-55 ~ +175	°C

Electrical Characteristics at Tvj= 25°C (unless otherwise specified)

Deceded:	Ob.ala	Combata Conditions		Characteristics		
Description	Symbols	Conditions	Min	Тур	Max	Unit
Collector-emitter breakdown voltage	V _{(BR)CES}	V _{GE} = 0V, I _C = 0.25mA	1200		(4)	٧
Zero gate voltage collector current	ICES	V _{CE} = 1200V, V _{GE} = 0V	9.54	878	200	μА
Gate-emitter leakage current	IGES	V _{CE} = 0V, V _{GE} = ±20V		(3-1)	±200	nA
Gate-emitter threshold voltage	V _{GE(th)}	V _{CE} = V _{GE} , I _C = 250uA	5.0	5.8	6.6	V
Collector-emitter saturation voltage	V _{CE(sat)}	V _{GE} = 15V, I _C = 75A T _{vj} = 25°C T _{vj} = 175°C		1.6	2.25	V
Input capacitance	Cies	V - 00/ V - 0V		17800		pF
Output capacitance	Coes	V _{CE} = 25V, V _{GE} = 0V		237	0.00	pF
Reverse transfer capacitance	Cres	f= 1MHz		69		pF
Gate charge	Q _G	V _{CC} = 960V, I _C = 75A, V _{GE} = 15V		607		nC
Forward voltage drop	V _F	I _F = 75A T _{vj} = 25°C T _{vj} = 175°C		2.0 1.7	3.0	V

Switching Characteristics at Tvj= 25°C

Ddtl	Oh ala	Sambala Canditions		Characteristics		
Description	Symbols	Conditions	Min	Тур	Max	Unit
IGBT Characteristics	- 25					
Turn-on delay time	td(on)		92 - 70 Y	115	V 858	ns
Rise time	tr	V _{cc} = 600V	9.50	79	0.050	ns
Turn-off delay time	t _{d (off)}	Ic= 75A		314		ns
Fall time	tr	Vœ= 15V		104	•	ns
Turn-on energy	Eon	R _G = 10Ω	(*)	5.7		mJ
Turn-off energy	Eoff	Inductive load		3.4		mJ
Total switching energy	Ets			9.1	-	mJ
Diode Characteristics						
Diode reverse recovery time	trr	V _{cc} = 600V		312	-	ns
Diode reverse recovery charge	Qrr	I _F = 75A	Sav I	2.5		μC
Diode peak reverse recovery current	Irrm	di _F /d _t = 500A/µs	152 Y]	20.1		Α

Switching Characteristics at Tvj= 175°C

Desembles	Ob-st-	0	Characteristics			
Description	Symbols	Conditions	Min	Тур	Max	Unit
IGBT Characteristics						901
Turn-on delay time	td(on)		1 2	92		ns
Rise time	tr	Vcc= 600V		81		ns
Turn-off delay time	td(off)	Ic= 75A	-	364	850 7	ns
Fall time	tr	Vœ= 15V		184	9.50	ns
Turn-on energy	Eon	R _G = 10Ω	-	9.2		mJ
Turn-off energy	E _{off}	Inductive load	-	4.9		mJ
Total switching energy	Ets		-	14.1		mJ
Diode Characteristics	95	5	7.5			
Diode reverse recovery time	ter	Vcc= 600V	12	532	8,465	ns
Diode reverse recovery charge	Qrr	I= 75A	-	11.2		μС
Diode peak reverse recovery current	Irrm	dir/d= 500A/µs	-	44.5	2.65	Α



Thermal Resistance

	O	(Characteristics			
Items	Symbols	Min	Тур	Max	Unit	
Thermal resistance, junction-ambient	R _{th(i-a)}	850	(3-5)	50		
Thermal resistance, IGBT junction to case	Rin(i-c)	52.1	0021	0.2	°C /V	
Thermal resistance, diodes junction to case	R _{th(i-c)}	((*)	30-33	0.3		

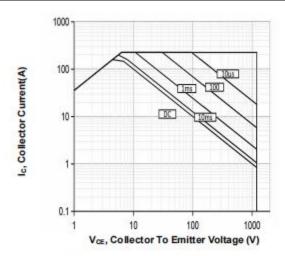


Figure 1. Forward bias safe operating area (D= 0, T_C= 25°C, T_{vi}≤ 175°C; V_{GE}= 15V)

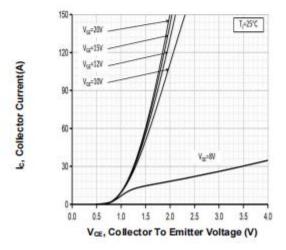


Figure 3. Typical output characteristic $(T_{\text{vl}}=25^{\circ}\text{C})$

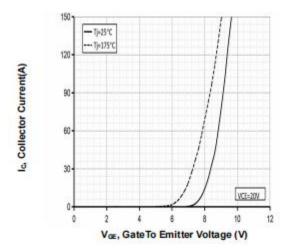


Figure 5. Typical transfer characteristic (Vox= 20V)

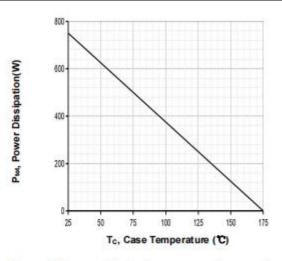


Figure 2. Power dissipation vs. case temperature (T_N≤ 175*C)

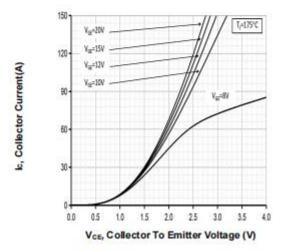


Figure 4. Typical output characteristic (T_{vi}= 175°C)

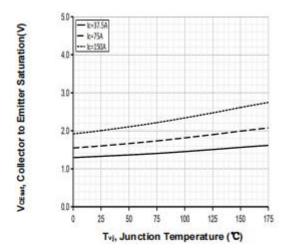


Figure 6. Typical collector-emitter saturation voltage vs. T_{vj} (Vos= 20V)

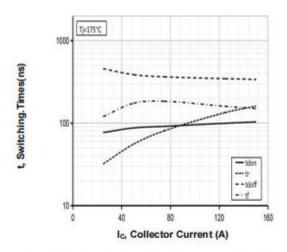


Figure 7. Typical switching times vs. collector current (Ind. load, T_{vj}= 175*C, V_{CE}= 600V, V_{GE}= 15/0V, R_G=10Ω)

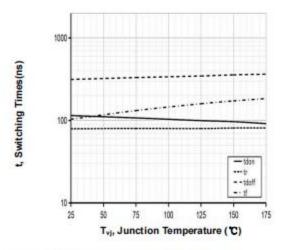


Figure 9. Typical switching times vs. T_{vj} (Ind. Load, V_{CE} = 600V, V_{OE} = 15/0V, I_{C} = 75A, R_{G} = 10 Ω)

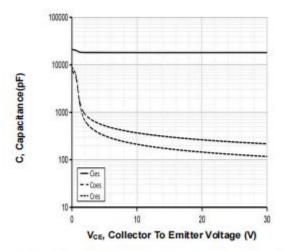


Figure 11. Typical capacitance vs. collector-emitter voltage (Vos= 0V, f= 1MHz)

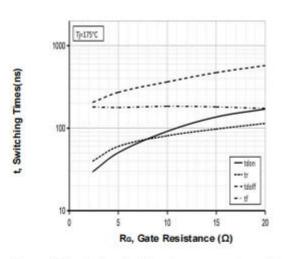


Figure 8. Typical switching times vs. gate resistor (Ind. Load, T_{vi}= 175*C, V_{CE}= 600V, V_{GE}= 15/0V, I_C= 75A)

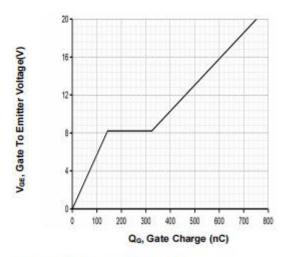


Figure 10. Typical gate charge (I_c= 75A)

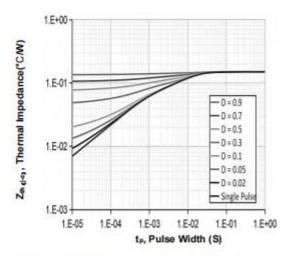


Figure 12. IGBT transient thermal impedance (D= t₀/T)

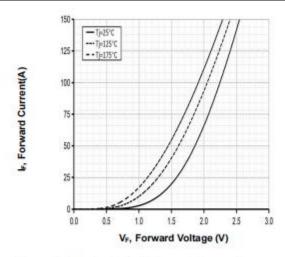


Figure 13. Typical diode forward current vs. forward voltage

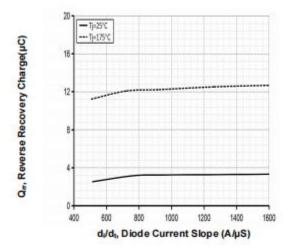


Figure 15. Typical reverse recovery charge vs. diode current slope (V_R = 600V)

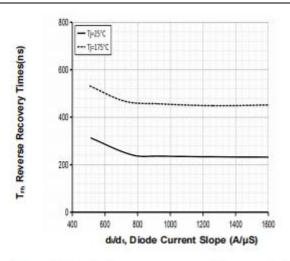


Figure 14. Typical reverse recovery time vs. diode current slope (V_R= 600V)

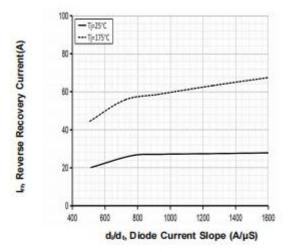
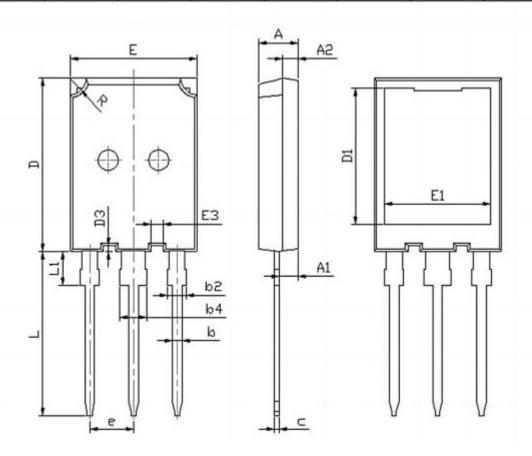


Figure 16. Typical reverse recovery current vs. diode current slope (V_R= 600V)

TO-247PLUS-3L Package Outline

7716 V		30	100	- 20	UNIT: mm		
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
Α	4.80	5. 00	5. 20	D3	0.53	0. 68	0.83
A1	2. 21	2.40	2. 61	E	15. 50	15. 80	16. 10
A2	1.85		2. 15	E1	13. 10	13. 30	13.50
b	1.07	1. 20	1. 33	E3	1.30	1. 45	1.60
b2	1.90		2. 16	e		5. 44	
Ь4	2.90		3. 20	L	19. 62	19. 92	20. 22
С	0.52	0.60	0. 68	L1			4. 30
D	20. 70	21. 00	21.30	R	1.85	2.00	2. 15
D1	16. 25	16. 55	16.85				



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